

Electronic Patent Application Fee Transmittal

Application Number:	10809566			
Filing Date:	25-Mar-2004			
Title of Invention:	WAFER BACK SURFACE TREATING METHOD AND DICING SHEET ADHERING APPARATUS			
First Named Inventor/Applicant Name:	Yuji Okawa			
Filer:	Kerry S. Taylor/Chiaki Kokka			
Attorney Docket Number:	UNIU79.022AUS			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1400	1400
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
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Total in USD (\$)				1700